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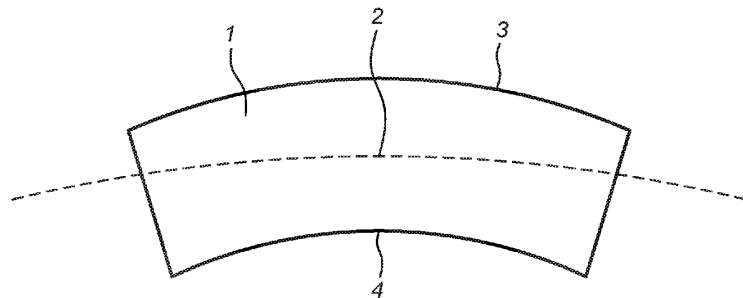


Fig. 2

(57) Abstract: The invention relates to a method for forming saw-cuts into a semiconductor product, comprising the steps of: gripping a semiconductor product with a carrier having a X, Y oriented holding surface; determining the position in X, Y orientation of a semiconductor product held by the carrier; controlling a relative movement of the carrier and a saw blade for cutting the semiconductor product based on the position of the semiconductor product held by the carrier. Wherein besides the position also the shape in X, Y orientation of the semiconductor product held by the carrier is detected, and wherein during the cutting of the semiconductor product the saw blade and the carrier are moved with respect to each other in X and Y orientations to saw non-linear cuts in the semiconductor product. The invention further relates to a sawing device for forming saw-cuts into a semiconductor product.



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